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Notification Number:			20161031000			Notification Date:		Nov. 7, 2016	
Title: Datasheet for TMS320F28335/TMS320F28334/TMS320F28333/TMS320F28332 TMS320F28235/TMS320F28234/MS320F28232									
Customer Contact: PCN Manager		Nanager	,		Quality Ser	rvices			
Change	Change Type:								
Assembly Site					Design Wa		Wafer	Bump Site	
Assembly Process				\boxtimes	Data Sheet			Wafer	Bump Material
Assembly Materials					Part number of			Wafer	Bump Process
Med	Mechanical Specification Test Site				Wafer	Fab Site			
Packing/Shipping/Labeling		ng		Test Process			Wafer	Fab Materials	
								Wafer	Fab Process
				N	otification D	etails			
Descrip	tion of Chang	je:							
Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is updated as seen in the change revision history below:									
TMS320F28335, TMS320F28334, TMS320F28333, TMS320F28332 TMS320F28235, TMS320F28234, TMS320F28232 SPRS439N – JUNE 2007 – REVISED OCTOBER 2016 TEXAS INSTRUMENTS www.ti.com									

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•	Section 6.2.11 (Serial Peripheral Interface (SPI) Module (SPI-A)): Updated "Rising edge with phase delay"	
	clocking scheme.	<u>144</u>
•	Figure 6-23 (F28335, F28333, F28235 Memory Map): Changed 0x38 0090 to 0x38 0091. Changed "ADC	
	Calibration Data" to "ADC Calibration Data and PARTID (Secure Zone)".	<u>159</u>
•	Figure 6-24 (F28334, F28234 Memory Map): Changed 0x38 0090 to 0x38 0091. Changed "ADC Calibration	
	Data" to "ADC Calibration Data and PARTID (Secure Zone)"	160
•	Figure 6-25 (F28332, F28232 Memory Map): Changed 0x38 0090 to 0x38 0091. Changed "ADC Calibration	
	Data" to "ADC Calibration Data and PARTID (Secure Zone)"	161
•	Table 6-26 (Wait States): Updated COMMENTS for XINTF.	
•	Table 6-31 (Device Emulation Registers): Added PARTID and CLASSID for TMS320F28333	167
•	Figure 6-34 (Watchdog Module): Updated figure.	178
•	Section 7 (Applications, Implementation, and Layout): Added section.	180
•	Section 8 (Device and Documentation Support): Added section.	181
•	Section 8.1 (Getting Started): Updated section.	181
•	Figure 8-1 (Example of F2833x, F2823x Device Nomenclature): Added 28333 under DEVICE.	182
•	Figure 8-1: Updated TECHNOLOGY: Changed "1.9-V Core" to "1.9-V or 1.8-V Core"	182
•	Section 8.3 (Tools and Software): Added section.	183
•	Table 8-1 (TMS320F2833x BSDL and IBIS Models): Added TMS320F28333.	185
	Section 8.4 (Documentation Support): Updated section.	
•	Section 9 (Mechanical Packaging and Orderable Information): Added section.	
•	Section 9.1 (Packaging Information): Updated section.	

The datasheet number will be changing.

Device Family	Change From:	Change To:
TMS320F2833x, TMS320F2823x	SPRS439M	SPRS439N

These changes may be reviewed at the datasheet links provided.

http://www.ti.com/lit/ds/symlink/tms320f28335.pdf

Reason for Change:

To more accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device

Changes to product identification resulting from this notification:

None.

TMS320F28232PTPQ	TMS320F28234ZJZQR	TMS320F28332PTPQ	TMS320F28335PTPQ
TMS320F28232ZJZQ	TMS320F28235PTPQ	TMS320F28332ZJZQ	TMS320F28335ZJZQ
TMS320F28234PTPQ	TMS320F28235ZJZQ	TMS320F28334PTPQ	TMS320F28335ZJZQR
TMS320F28234ZJZQ	TMS320F28235ZJZQR	TMS320F28334ZJZQ	

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